SCES172A - DECEMBER 1998 - REVISED FEBRUARY 1999

<ul> <li>Member of the Texas Instruments Widebus™ Family</li> </ul>		V, OR E (TOP VI	DL PACKAGE EW)
<ul> <li>EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process</li> </ul>	NC [ NC [		56 ] GND 55 ] NC
<ul> <li>Outputs Have Equivalent 26-Ω Series</li> </ul>	Y1	1	54 A1
Resistors, So No External Resistors Are	-	1	E
Required	GND [		53 GND
<ul> <li>ESD Protection Exceeds 2000 V Per</li> </ul>	Y2 [		52 A2
MIL-STD-883, Method 3015; Exceeds 200 V	Y3 [	1	51 A3
Using Machine Model (C = 200 pF, R = 0)		1	50 V <sub>CC</sub>
	Y4 [	1	
Latch-Up Performance Exceeds 250 mA Per	Y5 [		48 A5
JESD 17	Y6 [	1	47 A6
<ul> <li>Package Options Include Plastic Shrink</li> </ul>	GND		46 GND
Small-Outline (DL), Thin Shrink	Y7 [	1	45 A7
Small-Outline (DGG), and Thin Very	Y8 [	1	44 A8
Small-Outline (DGV) Packages	Y9 [		43 A9
	Y10	1	42 A10
description	Y11 [	1	41 A11
This 18-bit universal bus driver is designed for	Y12	1	40 A12
1.65-V to 3.6-V $V_{CC}$ operation.	GND [		39 GND
	Y13	1	38 A13
Data flow from A to Y is controlled by the	Y14 [	1	37 A14
output-enable (OE) input. The device operates in	Y15		36 A15
the transparent mode when the latch-enable $(\overline{LE})$	Vcc [		35 V <sub>CC</sub>
input is low. The A data is latched if the clock (CLK)	Y16	1	34 🛛 A16
input is held at a high or low logic level. If LE is	Y17 [		33 🛛 A17
high, the A data is stored in the latch/flip-flop on	GND [		32 GND
the low-to-high transition of CLK. When OE is	Y18	26	31 A18

NC - No internal connection

OE

27 28 30 CLK

29 GND

The outputs, which are designed to sink up to 12 mA, include equivalent 26- $\Omega$  resistors to reduce overshoot and undershoot.

The SN74ALVC162834 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC and Widebus are trademarks of Texas Instruments Incorporated.

high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to V<sub>CC</sub>

through a pullup resistor; the minimum value of the resistor is determined by the current-sinking

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

capability of the driver.



Copyright © 1999, Texas Instruments Incorporated

SCES172A - DECEMBER 1998 - REVISED FEBRUARY 1999

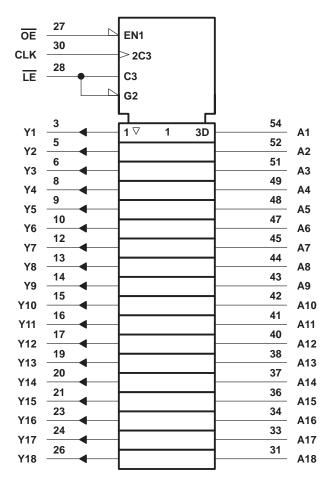
#### **FUNCTION TABLE**

	INPUTS								
OE	LE	CLK	Α	Y					
Н	Х	Х	Х	Z					
L	L	Х	L	L					
L	L	Х	Н	н					
L	Н	$\uparrow$	L	L					
L	Н	$\uparrow$	Н	н					
L	Н	н	Х	Y0 <sup>†</sup> Y0 <sup>‡</sup>					
L	Н	L	Х	Y0‡					

<sup>†</sup>Output level before the indicated steady-state input conditions were established, provided that CLK is high before LE goes high <sup>‡</sup>Output level before the indicated steady-state

input conditions were established

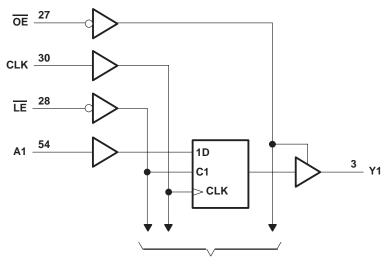
#### logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



To 17 Other Channels

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>		–0.5 V to 4.6 V
Input voltage range, VI (see Note 1)		$\ldots$ –0.5 V to 4.6 V
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)		-0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, IIK (VI < 0)		–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)		
Continuous output current, IO		±50 mA
Continuous current through each V <sub>CC</sub> or GND		±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	: DGG package	81°C/W
	DGV package	
	DL package	
Storage temperature range, T <sub>stg</sub>		$\dots$ –65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



## SN74ALVC162834 **18-BIT UNIVERSAL BUS DRIVER** WITH 3-STATE OUTPUTS SCES172A – DECEMBER 1998 – REVISED FEBRUARY 1999

#### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
VIH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V		0.8	
VI	Input voltage		0	VCC	V
Vo	Output voltage		0	VCC	V
		V <sub>CC</sub> = 1.65 V		-2	
1		V <sub>CC</sub> = 2.3 V		-6	
ЮН	High-level output current	V <sub>CC</sub> = 2.7 V		-8	mA
		V <sub>CC</sub> = 3 V		-12	
		V <sub>CC</sub> = 1.65 V		2	
		V <sub>CC</sub> = 2.3 V		6	0
IOL	Low-level output current	V <sub>CC</sub> = 2.7 V		8	mA
		V <sub>CC</sub> = 3 V		12	
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V	
Т <sub>А</sub>	Operating free-air temperature	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCES172A - DECEMBER 1998 - REVISED FEBRUARY 1999

PA	ARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	түр†	MAX	UNIT
		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2	2		
		$I_{OH} = -2 \text{ mA}$	1.65 V	1.2			
	I <sub>OH</sub> = -4 mA	2.3 V	1.9				
۷он			2.3 V	1.7			V
		I <sub>OH</sub> = -6 mA	3 V	2.4			
		I <sub>OH</sub> = -8 mA	2.7 V	2			
		I <sub>OH</sub> = -12 mA	3 V	2			
		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.2	
		$I_{OL} = 2 \text{ mA}$	1.65 V			0.45	
V <sub>OL</sub>		I <sub>OL</sub> = 4 mA	2.3 V			0.4	
			2.3 V			0.55	V
		$I_{OL} = 6 \text{ mA}$	3 V			0.55	
		I <sub>OL</sub> = 8 mA	2.7 V			0.6	
		I <sub>OL</sub> = 12 mA	3 V			0.8	
lj –		$V_I = V_{CC}$ or GND	3.6 V			±5	μΑ
IOZ		$V_{O} = V_{CC} \text{ or } GND$	3.6 V			±10	μΑ
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	3.6 V			40	μΑ
∆ICC		One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> o	r GND 3 V to 3.6 V			750	μΑ
<u>C.</u>	Control inputs		2.2.1/		4		~F
Ci	Data inputs	$V_{I} = V_{CC} \text{ or } GND$	3.3 V		5.5		pF
Co	Outputs	$V_{O} = V_{CC} \text{ or } GND$	3.3 V		7		pF

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> =  $25^{\circ}$ C.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

				V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				‡		150		150		150	MHz
t Dulas duration	LE low		‡		3.3		3.3		3.3			
tw	Pulse duration	CLK high or low		‡		3.3		3.3		3.3		ns
		Data before CLK↑		‡		2.1		2.1		1.7		
t <sub>su</sub>	Setup time		CLK high	‡		2.3		2.3		1.9		ns
		Data before LE↑	CLK low	‡		1.9		1.9		1.5		
	Hold time	Data after CLK↑		‡		0.6		0.6		0.7		
<sup>t</sup> h		Data after LE↑	CLK high or low	‡		0.8		0.8		0.9		ns

<sup>‡</sup> This information was not available at the time of publication.



SCES172A - DECEMBER 1998 - REVISED FEBRUARY 1999

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = ± 0.2	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	= V <sub>CC</sub> ± 0.3	3.3 V 3 V	UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
fmax			†		150		150		150		MHz
	A			†	1	5.2		5	1	4.2	
<sup>t</sup> pd	LE	Y		†	1.3	6		6.8	1.3	5.8	ns
	CLK			†	1.4	6.8		6.1	1.4	5.4	
t <sub>en</sub>	OE	Ý		†	1.4	6.3		6.5	1.5	5.9	ns
<sup>t</sup> dis	OE	Y		†	1	4.4		5.2	1.8	5	ns

<sup>†</sup> This information was not available at the time of publication.

## switching characteristics from 0°C to 65°C, CL = 50 pF

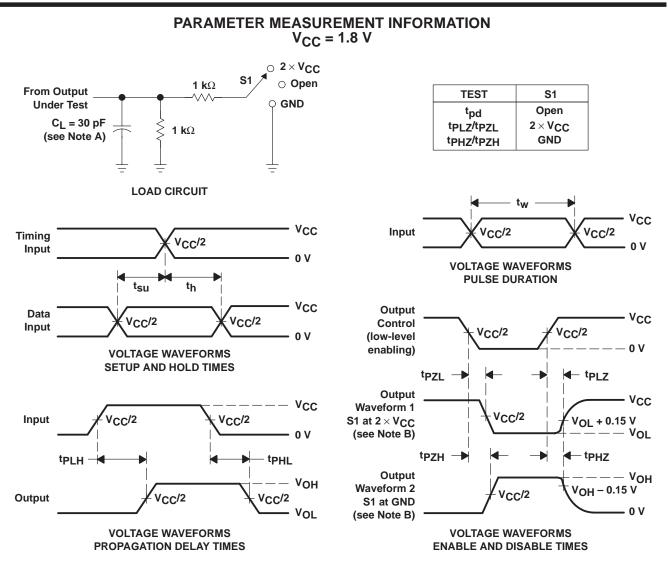
PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	V <sub>CC</sub> = ± 0.1	UNIT	
		(001-01)	MIN	MAX	
	A		1.4	3.9	
<sup>t</sup> pd	LE	Y	1.8	5.5	ns
	CLK		1.8	5.2	

## operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		PARAMETER TEST CONDITIONS			V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
					TYP	TYP	TYP	0
<u> </u>	Power dissipation	Outputs enabled	$C_{1} = 0$	f - 10 MHz	†	38	41	рF
Cpd	capacitance	Outputs disabled	C <sub>L</sub> = 0,	f = 10 MHz	†	13	15	рг

<sup>†</sup> This information was not available at the time of publication.



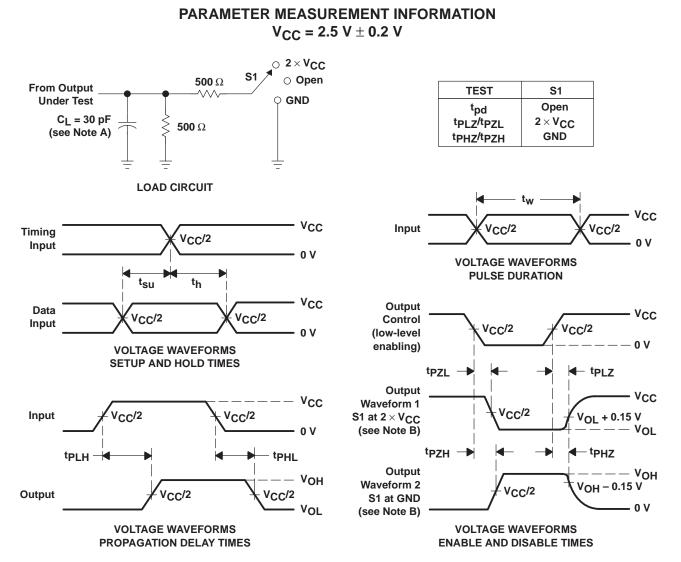


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. tPLH and tPHL are the same as tpd.

#### Figure 1. Load Circuit and Voltage Waveforms



SCES172A - DECEMBER 1998 - REVISED FEBRUARY 1999

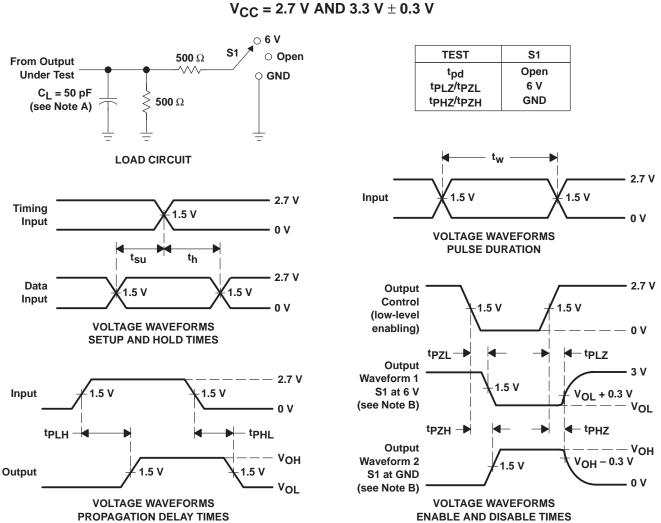


- NOTES: A. CL includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2 ns, t<sub>f</sub>  $\leq$  2 ns.

  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tPLZ and tPHZ are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tPLH and tPHL are the same as tpd.

#### Figure 2. Load Circuit and Voltage Waveforms





# PARAMETER MEASUREMENT INFORMATION V<sub>CC</sub> = 2.7 V AND 3.3 V $\pm$ 0.3 V

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
   Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   All input pulses are supplied by geographic the following characteristics: DBD < 10 MHz 7a = 50.0 t < 25 pc tr < 25 pc</li>
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.
- $\ensuremath{\mathsf{D}}\xspace.$  The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G. tPLH and tPHL are the same as tpd.

#### Figure 3. Load Circuit and Voltage Waveforms



#### **IMPORTANT NOTICE**

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1999, Texas Instruments Incorporated